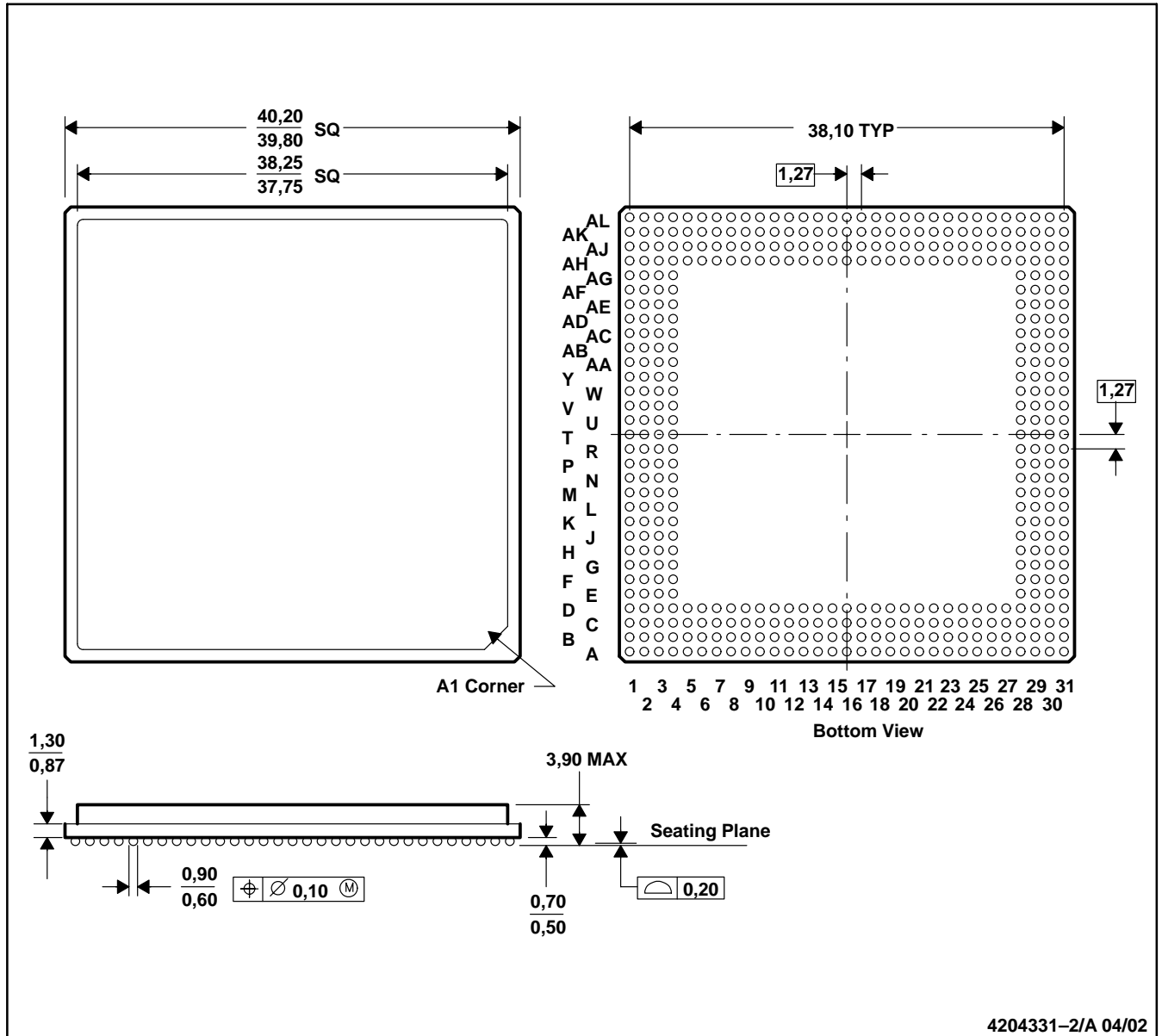


GPZ (S-PBGA-N432)

PLASTIC BALL GRID ARRAY



4204331-2/A 04/02

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Thermally enhanced plastic package with a heat slug (HSL).  
 D. Flip chip application only.

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